



GAU 2827

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Salam Akram

Serial No.: 09/853,111

Filed: May 10, 2001

For: Mounting Multiple Semiconductor
Dies In A Package

§ Group Art Unit:

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2827

Examiner:

A. Chambliss

Atty. Dkt. No.:

MCT.0012D1US
(97-0141)

Commissioner for Patents
Washington DC 20231

REPLY TO PAPER NO. 2

Sir:

In response to the office action mailed January 6, 2002, please amend the above-referenced patent application as follows:

In the Drawings:

Please amend the drawings as indicated in red on the attached figures.

In the Title:

Please amend the title to read:

"Method of Fabricating Mounted Multiple Semiconductor Dies in a Package".

In the Claims:

Please amend claim 15 as follows:

15. (Amended) A method for mounting multiple semiconductor dies on a single leadframe, comprising:
- stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another; and
 - wire bonding each of the semiconductor dies to the leadframe.

Date of Deposit: 2/1/02

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, Washington DC 20231.

Lisa O'Sullivan